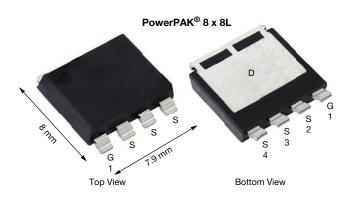


Vishay Siliconix

# Automotive N-Channel 100 V (D-S) 175 °C MOSFET



PRODUCT SUMMARY			
V <sub>DS</sub> (V)	100		
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.0092		
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$	0.0103		
I <sub>D</sub> (A) <sup>e</sup>	61		
Configuration	Single		

### **FEATURES**

- TrenchFET® Gen IV power MOSFET
- AEC-Q101 qualified
- 100 % R<sub>q</sub> and UIS tested
- Thin 1.9 mm height
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



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N-Channel MOSFET	o s

ORDERING INFORMATION	
Package	PowerPAK 8 x 8L
Lead (Pb)-free and halogen-free	SQJQ116EL (for detailed order number please see <a href="https://www.vishay.com/doc?79776">www.vishay.com/doc?79776</a> )

ABSOLUTE MAXIMUM RATING	<b>GS</b> (T <sub>C</sub> = 25 °C, unless	otherwise noted			
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		$V_{DS}$	100		
Gate-source voltage		$V_{GS}$	± 20	V	
Continuous drain current <sup>e</sup>	T <sub>C</sub> = 25 °C	1	61		
	T <sub>C</sub> = 125 °C	l <sub>D</sub>	35		
Continuous source current (diode conduction) e		I <sub>S</sub>	81	Α	
Pulsed drain current a, e		I <sub>DM</sub>	212		
Single pulse avalanche current	L = 0.1 mH	I <sub>AS</sub>	35		
Single pulse avalanche energy	L = U.1 Min	E <sub>AS</sub>	63	mJ	
Maximum power dissipation <sup>e</sup>	T <sub>C</sub> = 25 °C	Б	91	W	
	T <sub>C</sub> = 125 °C	$P_{D}$	30	VV	
Operating junction and storage temperature range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C	
Soldering recommendations (peak temperature) c			260	°C	

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	LIMIT	UNIT	
Junction-to-ambient	PCB mount b	$R_{thJA}$	42	°C/W	
Junction-to-case (drain) <sup>d</sup>		$R_{thJC}$	1.64		

#### Notes

- a. Pulse test; pulse width  $\leq 300 \,\mu\text{s}$ , duty cycle  $\leq 2 \,\%$
- b. When mounted on 1" square PCB (FR4 material)
- c. See solder profile (www.vishay.com/doc?73257)
- d. As per on JESD51-14
- e. Values based on RthJC and TC of 25 °C. Actual values achievable will be dependent on thermal characteristics of the complete system.



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PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT	
Static								
Drain-source breakdown voltage	$V_{DS}$	$V_{GS} = 0$ , $I_D = 250 \mu A$		100	-	-	V	
Gate-source threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	= V <sub>GS</sub> , I <sub>D</sub> = 250 μA	1.4	1.9	2.5	V	
Gate-source leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA	
Zero gate voltage drain current		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 100 V	-	-	1	μΑ	
	I <sub>DSS</sub>	$V_{GS} = 0 V$	V <sub>DS</sub> = 100 V, T <sub>J</sub> = 125 °C	-	-	50		
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 100 V, T <sub>J</sub> = 175 °C	-	-	500		
On-state drain current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = 10 V	$V_{DS} \ge 5 V$	50	-	-	Α	
Drain-source on-state resistance <sup>a</sup>		$V_{GS} = 4.5 \text{ V}$	I <sub>D</sub> = 20 A	-	0.0086	0.0103	Ω	
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 20 A	-	0.0077	0.0092		
	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 20 A, T <sub>J</sub> = 125 °C	-	-	0.0190		
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 20 A, T <sub>J</sub> = 175 °C	-	-	0.0240	1	
Forward transconductance b	9 <sub>fs</sub>	$V_{DS}$	= 15 V, I <sub>D</sub> = 40 A	-	150	-	S	
Dynamic <sup>b</sup>								
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 25 V, f = 1 MHz	-	4670	6538	pF	
Output capacitance	C <sub>oss</sub>			-	464	650		
Reverse transfer capacitance	C <sub>rss</sub>			-	29	41	1	
Total gate charge <sup>c</sup>	Qg			-	70	105		
Gate-source charge <sup>c</sup>	$Q_{gs}$	$V_{GS} = 10 \text{ V}$ $V_{DS} = 50 \text{ V}, I_D = 20 \text{ A}$		-	13	-	nC	
Gate-drain charge <sup>c</sup>	$Q_{gd}$			-	12	-	1	
Gate resistance	Rg	f = 1 MHz		0.4	1.0	1.6	Ω	
Turn-on delay time <sup>c</sup>	t <sub>d(on)</sub>	$V_{DD} = 50 \text{ V},  R_L = 2.5  \Omega,$ $I_D \cong 20 \text{ A},  V_{GEN} = 10 \text{ V},  R_g = 1  \Omega$		-	13	20		
Rise time <sup>c</sup>	t <sub>r</sub>			-	4	8		
Turn-off delay time <sup>c</sup>	t <sub>d(off)</sub>			-	34	51	- ns	
Fall time <sup>c</sup>	t <sub>f</sub>			-	6	9		
Source-Drain Diode Ratings and Charac	teristics <sup>b</sup>							
Pulsed current <sup>a</sup>	I <sub>SM</sub>			-	-	212	Α	
Forward voltage	V <sub>SD</sub>	I <sub>F</sub> = 40 A, V <sub>GS</sub> = 0 V		-	0.7	1.1	V	
Body diode reverse recovery time	t <sub>rr</sub>	l <sub>F</sub> = 15 A, di/dt = 100 A/μs		-	43	86	ns	
Body diode reverse recovery charge	Q <sub>rr</sub>			-	77	154	nC	
Reverse recovery fall time	ta			-	36	-		
Reverse recovery rise time	t <sub>b</sub>			_	7	_	ns	
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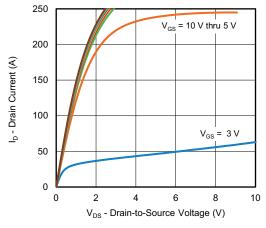
## Notes

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%$
- b. Guaranteed by design, not subject to production testing
- c. Independent of operating temperature

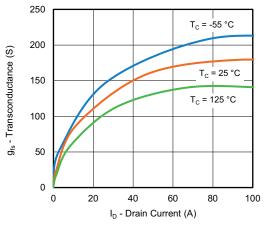
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



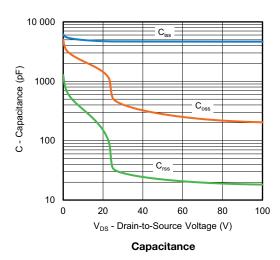
## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)

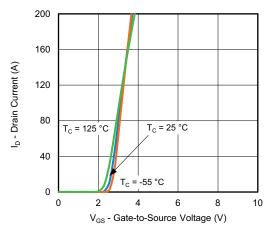


## **Output Characteristics**

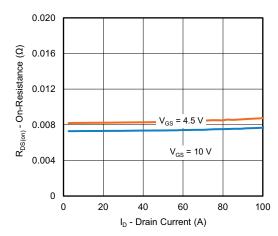


Transconductance

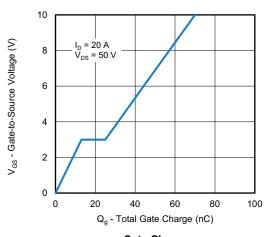




**Transfer Characteristics** 



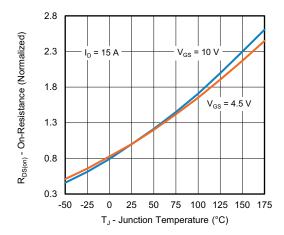
**On-Resistance vs. Drain Current** 



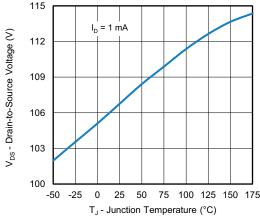
**Gate Charge** 



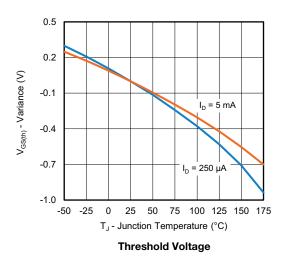
## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)

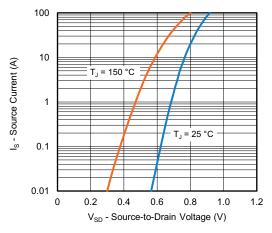


On-Resistance vs. Junction Temperature

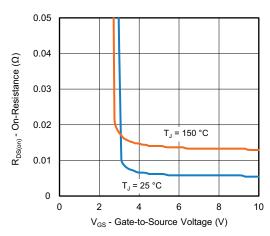


Drain Source Breakdown vs. Junction Temperature

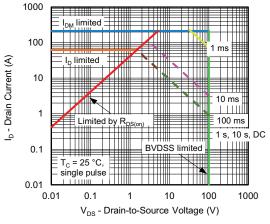




**Source Drain Diode Forward Voltage** 



On-Resistance vs. Gate-to-Source Voltage



Safe Operating Area

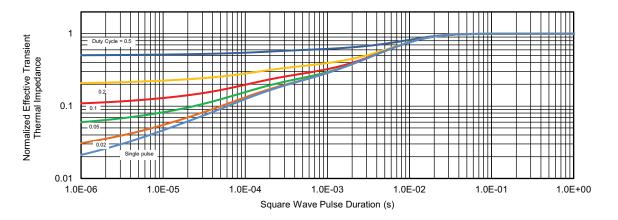
### Note

a.  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

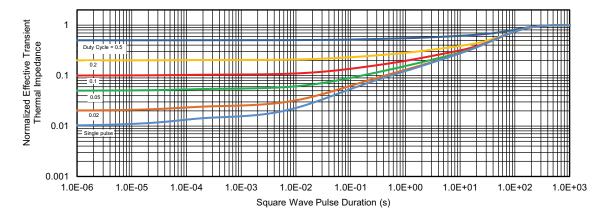
For technical questions, contact: automostech



## THERMAL RATINGS (T<sub>A</sub> = 25 °C, unless otherwise noted)



### Normalized Thermal Transient Impedance, Junction-to-Case



Normalized Thermal Transient Impedance, Junction-to-Ambient

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg?62252">www.vishay.com/ppg?62252</a>.



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